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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10055298	FILING DATE 01/23/2002	CLASS 257 438	SUBCLASS 712	GAU 2829	EXAMINER LUAN THAI
**APPLICANTS: Akram Salman; Wood Alan; 2227					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 09/885,615 06/20/2001					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 4376.1US (99-0660.1)	
TITLE : Method and apparatus for conducting heat in a flip-chip assembly					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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